

**Amendments to the Claims:**

If entered, this listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1 – 43. (Canceled)

44. (Currently Amended) A method to form a switching device, said method comprising:

providing a conductive loaded, resin-based material comprising micron  
conductive fiber ~~conductive material~~ in a resin-based host wherein said micron

5 conductive fiber has a diameter of between 3  $\mu$ m and 12  $\mu$ m and wherein the  
ratio, by weight, of said micron conductive fiber to said resin host is between 0.20  
and 0.40; and

molding said conductive loaded, resin-based material into a conductive pill  
in a switching device wherein said switching device comprises:

10 a conductive terminal; and

a conductive pill that moves between an open  
position and a closed position.

45. (Currently Amended) The method according to Claim 44 wherein said micron conductive fiber is nickel plated carbon fiber, stainless steel fiber, copper fiber, silver fiber or combinations thereof ~~the ratio, by weight, of said conductive materials to said resin host is between about 0.20 and about 0.40.~~

46. (Currently Amended) The method according to Claim 44 further comprising ~~wherein the conductive materials comprise~~ a conductive powder.

47. (Currently Amended) The method according to Claim ~~46~~ 44 wherein said conductive powder is nickel, copper, silver, or is a material plated with nickel, copper, or silver ~~conductive materials comprise a micron conductive fiber.~~

48. (Currently Amended) The method according to Claim ~~46~~ 44 wherein said conductive powder is carbon, graphite, or an amine-based material ~~conductive materials comprise a combination of conductive powder and conductive fiber.~~

49. (Original) The method according to Claim 44 wherein said molding comprises:

injecting said conductive loaded, resin-based material into a mold;

curing said conductive loaded, resin-based material; and

removing said conductive pill from said mold.

50. (Original) The method according to Claim 44 wherein said molding comprises:

injecting said conductive loaded, resin-based material into a chamber;

extruding said conductive loaded, resin-based material out of said

5 chamber through a shaping outlet; and

curing said conductive loaded, resin-based material to form said conductive pill.

51. (Original) The method according to Claim 50 wherein said step of extruding forms a rod of said conductive loaded, resin-based material and further comprising cutting said extruded conductive loaded resin-based material to form said conductive pill.

52. (Original) The method according to Claim 44 further comprising forming a metal layer around said conductive loaded, resin-based material.

53. (Original) The method according to Claim 52 wherein said step of forming a metal layer around said conductive loaded, resin-based material is by plating or by coating said metal layer.